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**Themis Prodromakis**, University of Southampton, UK

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## Third International Symposium on Memristive Systems (MEMRISYS) Call for Participation

**M**emristor technology will play a leading role in the design and fabrication of new circuits to overcome the limits posed by conventional CMOS technology. **MEMRISYS 2019** will provide a forum for the presentation and discussion of the latest results and the exploration of future directions across a wide range of fields: from materials to devices, circuits, systems, and applications.

With the increasing number of publications in topical journals, and conference proceedings, also resulting from numerous conference regular or special sessions, targeted workshops, and symposia, organized frequently each year, more interdisciplinary interactions are necessary for further progressing the state-of-the-art.

**MEMRISYS 2019** shall address this need by consolidating the underlying research communities in materials science, memristor theory, electronic devices, circuits, and systems, computation, and neuromorphic engineering in a single international conference, that will bring a new holistic view of developments in the field.

### Program Highlights - Plenary Speakers

We are pleased to announce our outstanding plenary speakers:

- **Geoffrey Burr**, IBM Almaden Research Center, San Jose, USA
- **Joshua Yang**, University of Massachusetts at Amherst, USA
- **Leon Chua**, University of California, Berkeley, USA
- **Stanley Williams**, Texas A&M University, USA
- **Iliia Valov**, Electronic Materials (IEM) Research Centre Jülich, Germany
- **Ronald Tetzlaff**, Technische Universität Dresden, Dresden, Germany

### The Conference Venue

Dresden is the center of «Silicon Saxony», Europe's largest microelectronics cluster and one of the world's most innovative ICT clusters, with the TU Dresden as its intellectual and R&D center. Dresden is situated in the south-eastern part of the Free State of Saxony, in the picturesque Elbe river valley. It offers various cultural treasures accumulated over time by the Saxon rulers. The foothills of the Erzgebirge Mountains characterize the delightful surroundings of the Saxon state capital.

### Contact and Further Information

Web site: <https://memrisys2019.org>

Email: [office@memrisys2019.org](mailto:office@memrisys2019.org)

**Important! Early-bird Registration until 3 June 2019**

